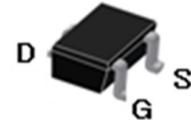
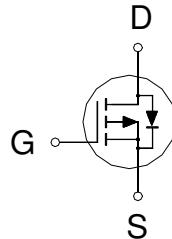




P-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV_{DSS}	-30V
$R_{DS(on)}(\text{MAX.})$	50m Ω
I_D	-4.5A



Pb-Free Lead Plating & Halogen Free



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_A = 25^\circ\text{C}$	I_D	-4.5	A
	$T_A = 70^\circ\text{C}$		-3.5	
Pulsed Drain Current ¹		I_{DM}	-18	
Power Dissipation	$T_A = 25^\circ\text{C}$	P_D	1.04	W
	$T_A = 70^\circ\text{C}$		0.66	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Ambient ³	$R_{\theta JA} (T \leq 10\text{sec})$		83	°C / W
	$R_{\theta JA} (\text{Steady State})$		120	

¹Pulse width limited by maximum junction temperature.

²Duty cycle $\leq 1\%$

³The device mounted on a 1 in² pad of 2 oz copper.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-30			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1	-1.5	-3	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = -24\text{V}, V_{\text{GS}} = 0\text{V}$			-1	μA
		$V_{\text{DS}} = -20\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$			-10	
On-State Drain Current ¹	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = -5\text{V}, V_{\text{GS}} = -10\text{V}$	-4.5			A
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = -10\text{V}, I_D = -4.5\text{A}$		42	50	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -3.5\text{A}$		66	85	
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = -5\text{V}, I_D = -4.5\text{A}$		16		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = -15\text{V}, f = 1\text{MHz}$		820		pF
Output Capacitance	C_{oss}			122		
Reverse Transfer Capacitance	C_{rss}			97		
Total Gate Charge ^{1,2}	Q_g	$V_{\text{DS}} = -15\text{V}, V_{\text{GS}} = -10\text{V}, I_D = -4.5\text{A}$		9		nC
Gate-Source Charge ^{1,2}	Q_{gs}			2.2		
Gate-Drain Charge ^{1,2}	Q_{gd}			2.5		
Turn-On Delay Time ^{1,2}	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = -15\text{V}, I_D = -1\text{A}, V_{\text{GS}} = -10\text{V}, R_{\text{GS}} = 6\Omega$		12		nS
Rise Time ^{1,2}	t_r			16		
Turn-Off Delay Time ^{1,2}	$t_{\text{d}(\text{off})}$			34		
Fall Time ^{1,2}	t_f			20		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_c = 25^\circ\text{C}$)						
Continuous Current	I_s				-3	A
Pulsed Current ³	I_{sm}				-12	
Forward Voltage ¹	V_{SD}	$I_F = I_s, V_{\text{GS}} = 0\text{V}$			-1.2	V

¹Pulse test : Pulse Width $\leq 300\text{ }\mu\text{sec}$, Duty Cycle $\leq 2\%$.

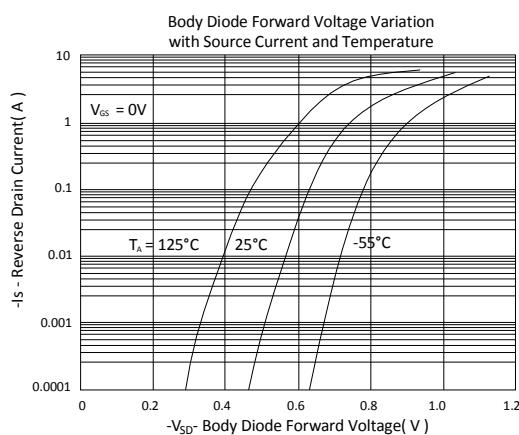
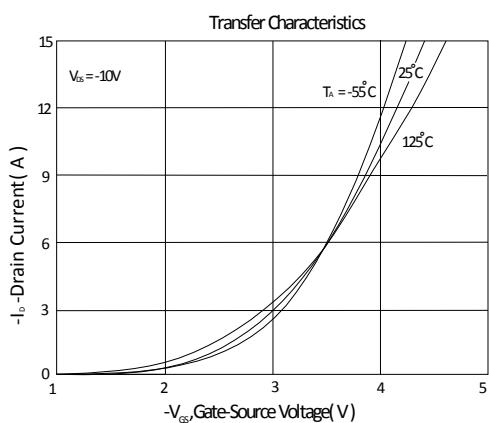
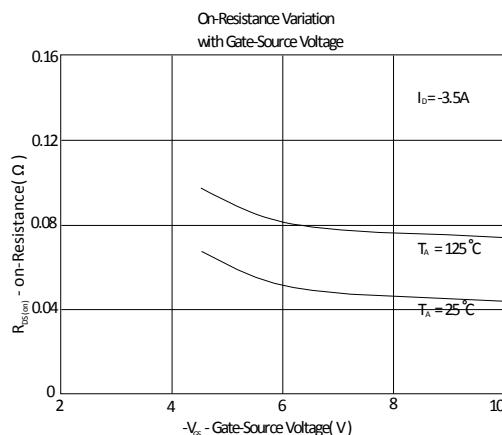
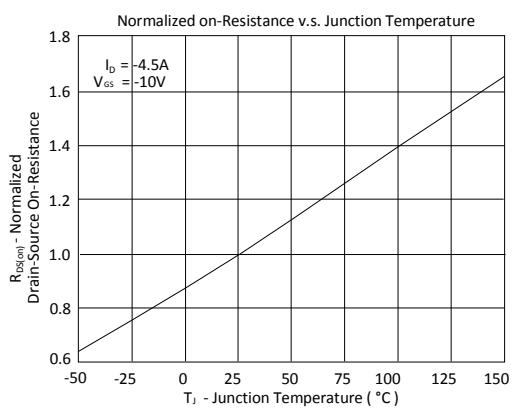
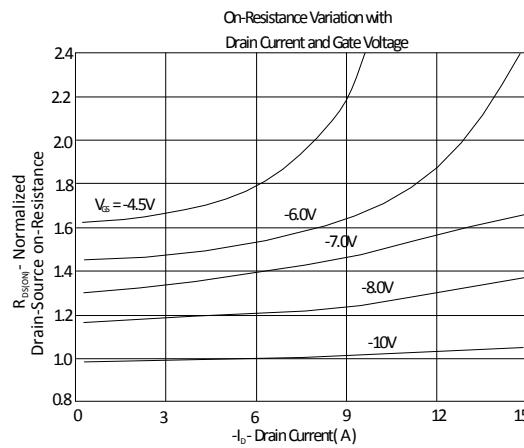
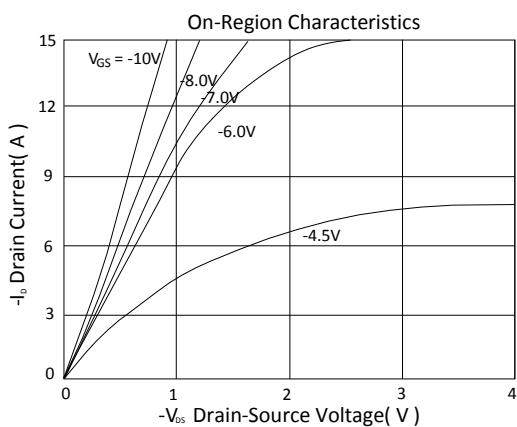
²Independent of operating temperature.

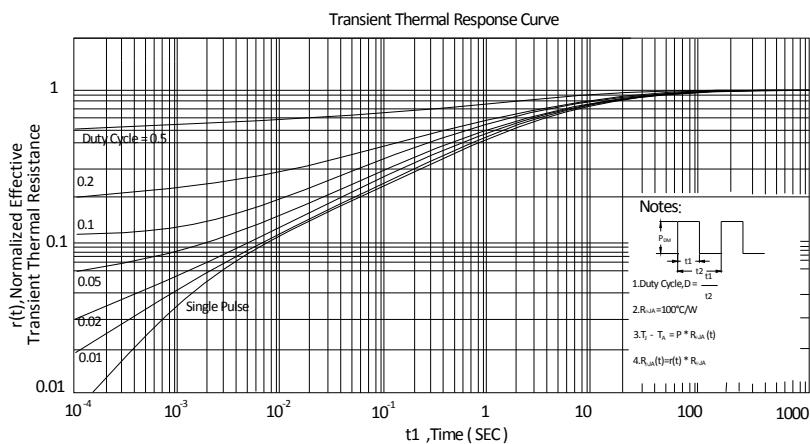
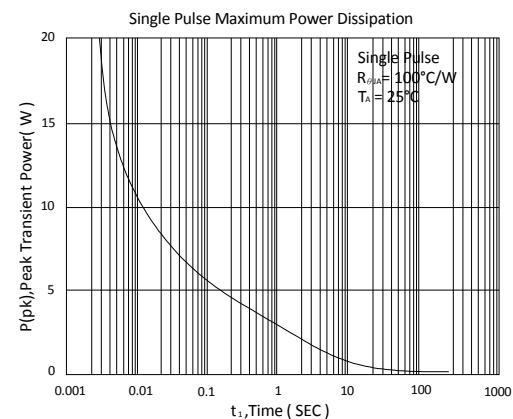
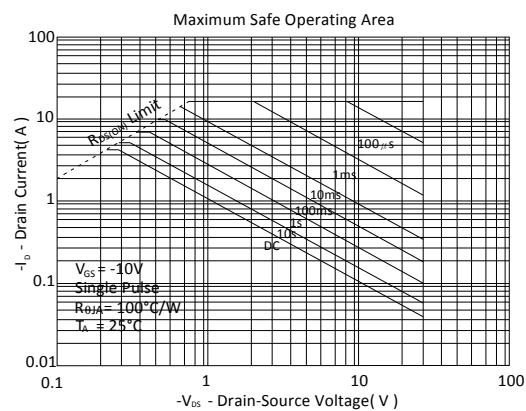
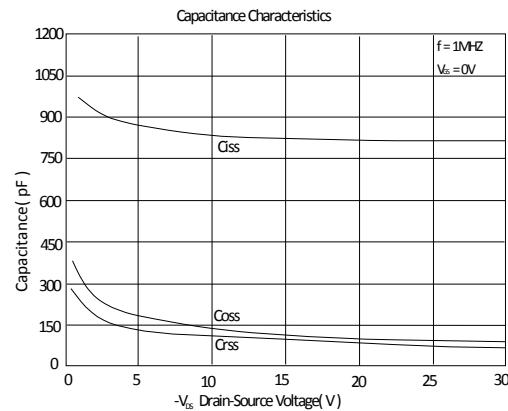
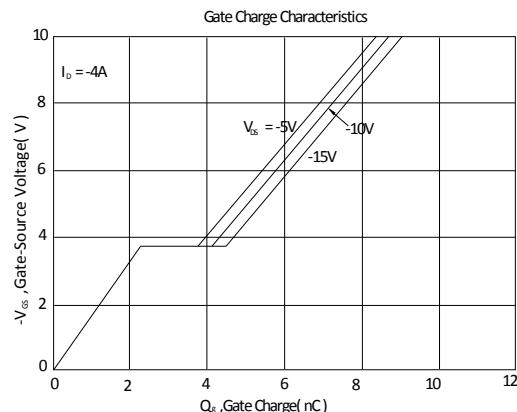
³Pulse width limited by maximum junction temperature.

EMC will review datasheet by quarter, and update new version.



TYPICAL CHARACTERISTICS

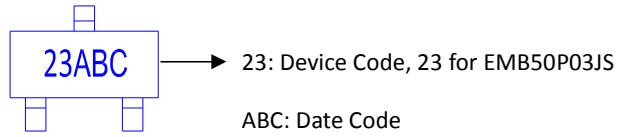




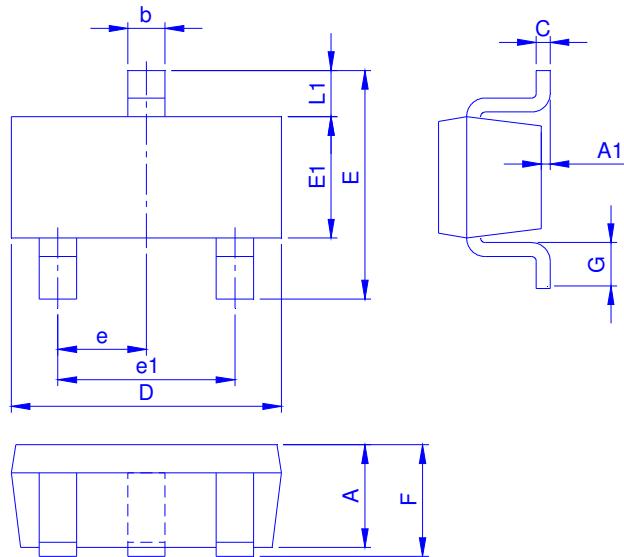


Ordering & Marking Information:

Device Name: EMB50P03JS for SOT23-3



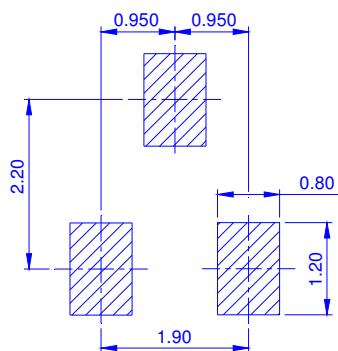
Outline Drawing



Dimension in mm

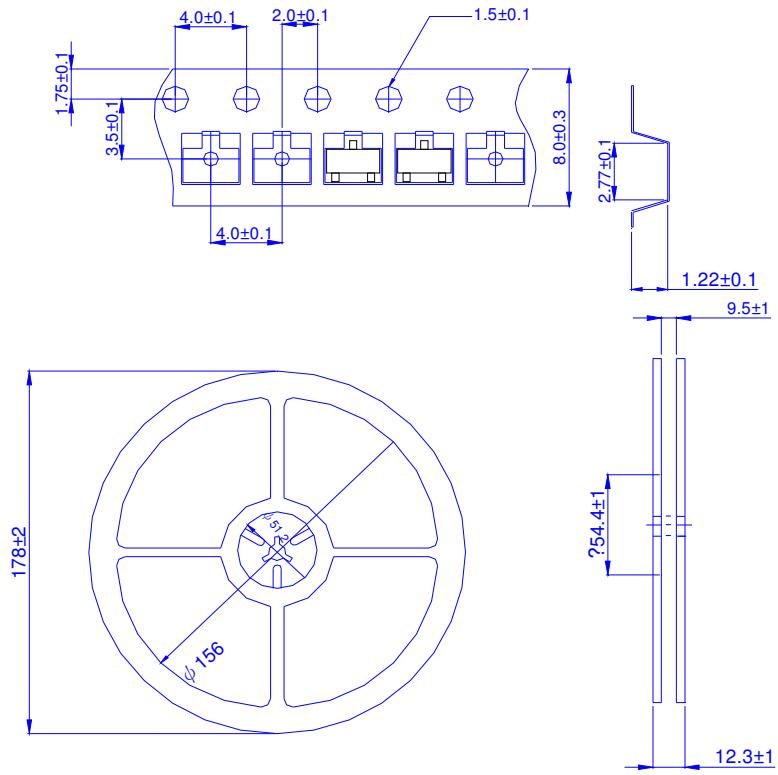
Dimension	A	A1	b	C	D	E	E1	e	e1	F	G	L1
Min.	0.70	-	0.30	0.080	2.80	2.10	1.20	0.90	1.80	0.80	0.30	0.54
Typ.	0.95	-	0.40	0.127	2.90	2.50	1.30	0.95	1.90	0.95	0.40	0.57
Max.	1.20	0.15	0.50	0.202	3.10	3.00	1.80	1.00	2.00	1.25	0.60	0.70

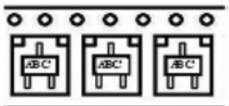
Footprint





- ◆ Tape&Reel Information:3000pcs/Reel(Dimension in millimeter)



產品別	SOT23-3
Reel 尺寸	7"
編帶方式	FEED DIRECTION  
前空格	50
後空格	50
裝箱數	
滿捲數量	3K
捲/內盒比	5 : 1
內盒滿箱數	15K
內/外箱比	12 : 1